Safety
- The furnaces are run at elevated temperatures of 400-900 C and use flammable, toxic, and corrosive gases.
- Buddy required for after hour usage

Process Restrictions
Material Restrictions
MOS CLEAN furnaces
- Silicon wafers, electronic grade SiC, or pure fused silica/quartz samples only
- No glass substrates, compound semiconductors, etc.
- No resists, polymers, or metals---exposed or unexposed
- Only samples with MOS and PECVD films are allowed
- No evaporated films, sputtered films, or spun films.
NON-MOS CLEAN furnaces
- Please see individual furnace instructions for allowed sample materials

Parameter Restrictions
- No changing of gas flows or process parameters without staff approval

Scheduling / Sign-up Restrictions
- 8 AM to 6 PM normal daytime hours no buddy needed.
- Lab buddy is required outside normal daytime hours. User and buddy do not need to be in the lab while tool is running.
- Reservation blocks greater than 8 hrs must be cleared by a MOS staff person prior to reserving the time

Requirements (Do Every Time)
- Samples must be MOS cleaned within 6 hrs prior to loading of the MOS clean furnaces
- Samples must remain in the MOS area boats when waiting to be loaded in the furnace
- Only use MOS tweezers or vacuum wand to load cleaned wafers, no metal or other tweezers allowed.
- Remove your wafers from the MOS boats at then end of the day!

Prohibitions (Never Do)
- NO unauthorized materials or wafers
- Never use tweezers or boats not from the MOS area.
- Never remove MOS boats, holders, or tweezers from the area
- DO NOT swap quartz boats from one furnace to another without MOS staff permission

Common Problems
<table>
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<tr>
<th>Problem:</th>
<th>Root Cause:</th>
<th>Solution:</th>
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Other Comments or Cautions

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